

FEATURES

For surface mounted applications

| Low profile package

| Glass Passivated Chip Junction

| Ideal for automated placement





Schematic Symbol

MECHANICAL DATA

Case: SOD-123FL	
Terminals: Solderable per MIL-STD-750, Method 2026	

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS AND CHARACTERISTICS ($T_A = 25$ °C)

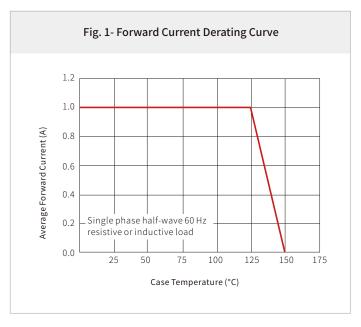
Parameter		Symbol	1N 4001W	1N 4002W	1N 4003W	1N 4004W	1N 4005W	1N 4006W	1N 4007W	Unit
Marking			A1	A2	А3	A4	A5	A6	Α7	
Maximum Repetitive Peak Reverse Voltage		V _{RRM}	50	100	200	400	600	800	1000	
Maximum RMS Voltage		V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		V _{DC}	50	100	200	400	600	800	1000	
Maximum Average Forward Rectified Current at T _c = 125 °C		I _{F(AV)}	1						А	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load		I _{FSM}	30							
Maximum Instantaneous Forward Voltage at 1 A		V _F	1.1						V	
Maximum DC Reverse Current	T _a =25°C					5				
at Rated DC Blocking Voltage	T _a =125°C	R	50					μΑ		
Typical Junction Capacitance (1)		CJ	8(TYP.)					pF		
Typical Thermal Resistance (2)		$R_{\theta JA}$	90					°C/W		
Operating and Storage Temperature Range		T_J , T_{STG}	-55 to +150					°C		

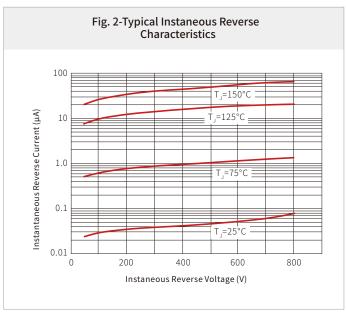
⁽¹⁾ Measured at 1 MHz and Applied Reverse Voltage Of 4V D.C

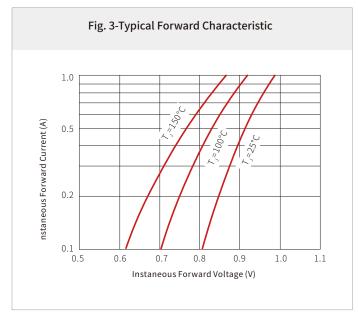
⁽²⁾ P.C.B. Mounted With 2.0" X 2.0" (5 X 5 cm) Copper Pad Areas.

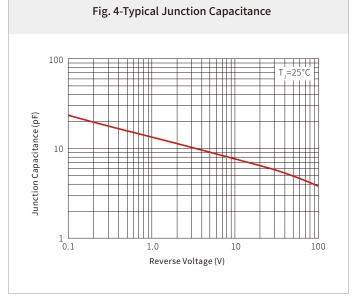


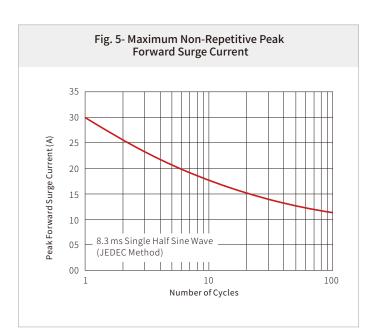
CHARACTERISTIC CURVES





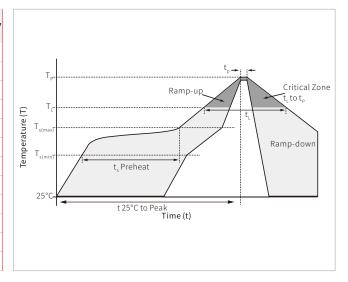






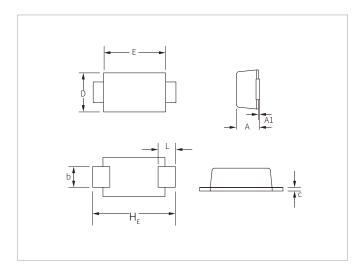
SOLDERING PARAMETERS

	Reflow Condition	Lead-free assembly		
	Temperature Max (T _{s(min)})	150°C		
Pre Heat	Temperature Max (T _{s(max)})	200°C		
	Time (min to max) (t _s)	60 – 180 secs		
Average ran	np up rate (Liquidus Temp (T_L) to peak	3°C/second max		
	3°C/second max			
Reflow	Temperature (T _L) (Liquidus)	217°C		
Kellow	Time (min to max) (t_L)	60 – 150 seconds		
Peak Temp	Peak Temperature (T _P)			
Time within	n 5°C of actual peak Temperature (t _p)	20 – 40 seconds		
Ramp-dow	n Rate	6°C/second max		
Time 25°C t	to peak Temperature (T _P)	8 minutes max.		
Do not exce	260°C			



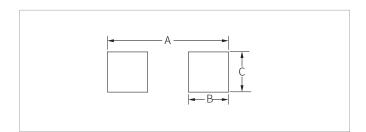


SOD-123FL PACKAGE INFORMATION



Ref.	Millim	neters	Inches		
ici.	Min.	Max.	Min.	Max.	
А	0.95	1.45	0.037	0.057	
A1	0.00	0.10	0.000	0.004	
b	0.70	1.20	0.028	0.047	
С	0.05	0.30	0.002	0.012	
D	1.50	2.00	0.059	0.079	
E	2.50	3.10	0.098	0.122	
L	0.35	0.90	0.014	0.035	
H _E	3.40	3.90	0.134	0.154	

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
А	4.20	0.165
В	1.50	0.059
С	1.20	0.047

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
1N4001W-1N4007W	SOD-123FL	3000PCS	7"







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By QR Code





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Machat

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